Chip-Size Package Structure and Method of the Same

ABSTRACT OF THE INVENTION

The method includes a step of picking and placing standard good dice on a base for obtaining an appropriate and wider distance between dice than the original distance of dice on a wafer. The method of the chip-size package comprises the steps of separating dice on a wafer and picking and placing the dice on a base and filling a first material layer on the base into a space among the dice on the base. A dielectric layer with first openings is patterned to expose a portion of a conductive line of the dice. A conductive material is filled into the first openings and on the dielectric layer. Subsequently, a second material layer is formed to have a second openings exposing the conductive material and then welding solder balls on the second openings.

(Fig. 7)